

초임계 CO₂ 내에서 CO₂와 nickel 도금액 계면에 미치는 비이온 계면활성제의 영향

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Effect of nonionic surfactant on interface between CO₂ and nickel plating solution in supercritical CO₂

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Introduction

Carbon dioxide(CO₂) has been regarded as a useful chemical having many advantages that it is cheap, nonflammable, nontoxic, chemically inert, recyclable, and readily accessible to supercritical region (T_c=31°C, P_c=7.38MPa)[1]. Especially, supercritical CO₂ have interesting solvating characteristics and provide greatly increased mass transfer rates in various fields such as an organic synthesis [2], electrochemical synthesis[3], and polymerization [4], etc. In spite of these advantages, CO₂ is also regarded as a poor solvent because the solubility of polar chemicals in CO₂ which is nonpolar is very low[5]. For this reason, the usage of CO₂ as a reaction solvent with water has lagged. Recently, the efforts to overcome these disadvantages of CO₂ are lively carried out by many chemists and engineers. One of these is the research about the formation of emulsion that polar chemicals of nano(nm) or micro(μm) size droplets in diameter were dispersed in CO₂[6-8]. It is desired that many polar chemicals will be soluble in CO₂, therefore, it is applied in various fields such as reaction, separation, electroplating process[9] etc. in supercritical CO₂. Among these, the electroplating process in supercritical CO₂ used the emulsion phenomena have been researched in my laboratory and this process will be resulted in reducing the aqueous plating solution. In formation of emulsion of immiscible phases like water or the aqueous plating solution and CO₂ emulsion, the interfacial tension (IFT) has an influence in formation of emulsion. Therefore these data are requisite as a basic information to understand the emulsion with CO₂. Unfortunately, the measurement of the IFT in high pressure CO₂ was hardly carried out except for several studies[10-11]. In this research, we manufactured the apparatus for IFT by using the capillary rise method in high pressure and measured the IFT of 1)water+CO₂ at 71°C, 2)nickel plating solution+CO₂ at 55°C, 3)nickel plating solution+CO₂+surfactant (0.1, 0.3 wt%) at 40°C, and 55°C, 4)Nickel plating solution+CO₂+ethanol (10, 20 vol%) at 55°C, and 5) nickel plating solution+CO₂+surfactant (0.1, 0.3 wt%)+ ethanol(10 vol%) at 40°C, and 55°C in the ranges of 0.1MPa~20.0 MPa by using the capillary rise method. The consistency of experimental data of water+CO₂ was confirmed by comparing of experimental data and others data[10-11] at 71°C.

Theory

IFT was measured by using capillary rise method and it was calculated by following equation.

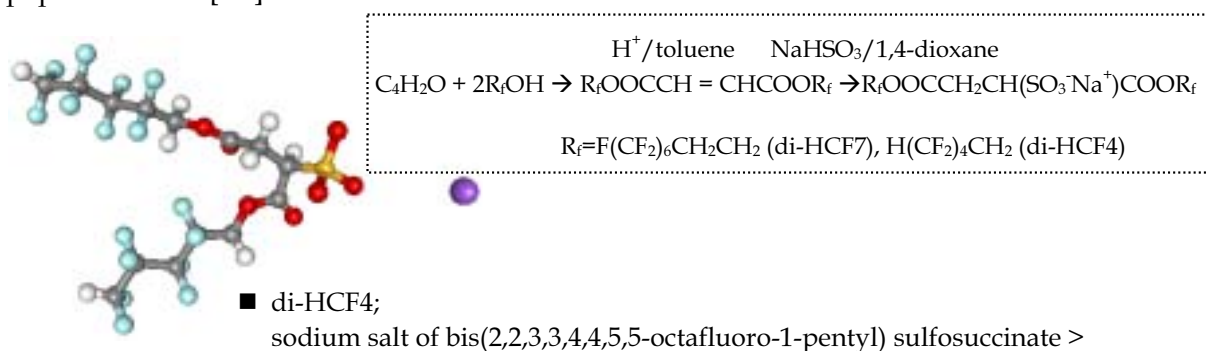
$$\gamma = \frac{1}{2}rg\left(h + \frac{r}{3}\right)\frac{\Delta\rho}{\cos\theta}$$

γ (mN/m) is interfacial tension, r (m) is the radius of the capillary, h (m) is the height of the meniscus above a flat liquid surface (for which ΔP must be zero), $\Delta\rho$ (g/ml) is the difference between density of CO₂ and density of water (or nickel plating solution), g (m/sec²) is the acceleration of gravity, θ is the contact angle (it is assumed as a 0°).

Experimental

Synthesis of surfactant and measurement of solubility The synthesis of fluorocarbon-hydrocarbon hybrid nonionic surfactants such as sodium salt of bis(2,2,3,3,4,4,5,5-octafluoro-1-pentanol) sulfosuccinate (di-HCF4) and the sodium salt of bis(3,3,4,4,5,5,6,6,7,7,8,8,8-tridecafluoro-octyl)-2-sulfosuccinate (di-HCF7) was reported by Zhao-Tie Liu and Can Erkey[13] and the measurement of solubility was expressed in previous paper[1] in detail.

Interfacial tension measurement The procedure for IFT measurement is shown in Chun's paper in detail[ref].



Results and Discussion

Two surfactants with 'CO₂ philic group' and hydrophilic group were synthesized. According to Tie Liu and Can Erkey's experiment, di-HCF 4 is soluble with an added water and better than di-HCF 7 in the water/CO₂ emulsion formation among these. By this result, di-HCF4 surfactant was chosen and used in measurement of IFT .

Interfacial tension measurement In this study, we measured the IFT of various systems such as 1) water + CO₂, 2) nickel plating solution + CO₂, 3) nickel plating solution + surfactant (di-HCF 4) + CO₂, 4) Nickel plating solution+CO₂+ethanol (10, 20 vol%)at 55°C, and 5) nickel plating solution + surfactant (di-HCF 4) + ethanol + CO₂. We considered the effect of temperature, surfactant, and ethanol on interface between CO₂ and nickel plating solution in supercritical CO₂.

Table 1. Properties of chemicals

chemical	γ^a (mN/m)	T(K)
Pure water	72.7	299.15
Nickel plating solution	43.0	299.15

γ^a (mN/m) : interfacial tension in atmospheric condition

1) **water + CO₂ system** IFT of water + CO₂ system was measured at 71°C for data consistency. IFT data of water + CO₂ at 71°C were compared with Hough's data [12] and Chun's data [13] and represented in Figure 1

2) **Nickel plating solution + CO₂ system** IFT of nickel plating solution + CO₂ system was measured at 55°C. IFT of this system was lower than that of water + CO₂ system because nickel ions that dissolved in water work as electrolytes. This result was shown in Figure 2.

3) **Nickel plating solution + CO₂ + di-HCF4 surfactant system** To investigate the effect on the concentration of di-HCF4 surfactant, we added the 0.1wt% and 0.3wt% in nickel plating solution and measured IFT of nickel plating solution + CO₂ + di-HCF4 system at 40°C, and 55°C. As the concentration of surfactant was higher, the IFT on between two fluids became lower.

This result was shown in Figure 3.

4) **Nickel plating solution + CO₂ + ethanol system**

IFT of nickel plating solution + CO₂ + ethanol (10vol%) system were measured at 55°C. Ethanol reduced IFT like Chun's study[13] that alcohol such as isopropyl alcohol, ethanol, methanol, and butanol reduce the IFT of water +CO₂. This result was shown in Figure 4.

5) **Nickel plating solution + CO₂ + di-HCF4 surfactant + ethanol system** To look into effect ethanol and surfactant at the same time, IFT of nickel plating solution + CO₂ + di-HCF4 surfactant (0.1, 0.3 wt %) + ethanol (10vol%) system were measured at 40°C, and 55°C. By experiments 3) and 4), the double effects of reduction in IFT was predicted. But, when IFT of solution with both ethanol and di-HCF4, it was increased. These results were shown in Figures 4 and 5.

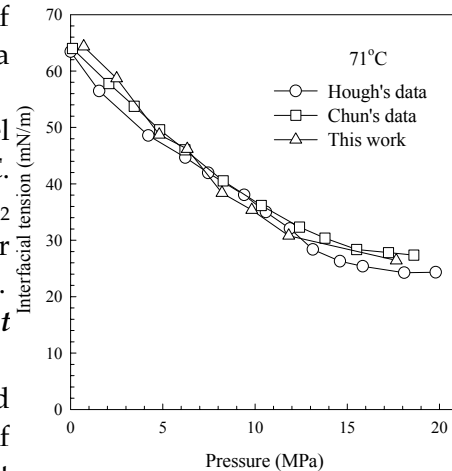


Figure 1. Comparison of IFT for CO₂ + Water mixture at 71°C

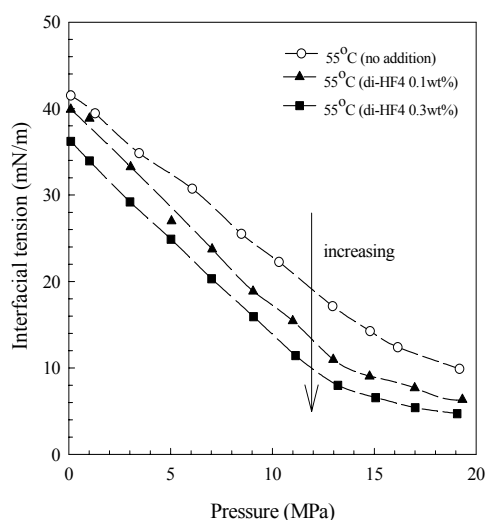


Figure 2. IFT of CO₂ + Nickel plating solution + di-HCF4 at 55°C

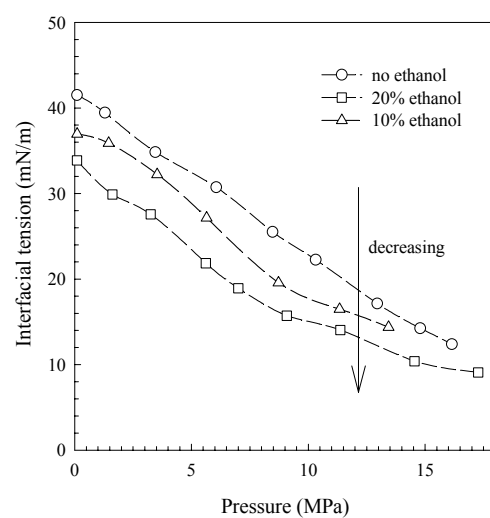


Figure 3. IFT of CO₂ + Nickel plating solution + ethanol at 55°C

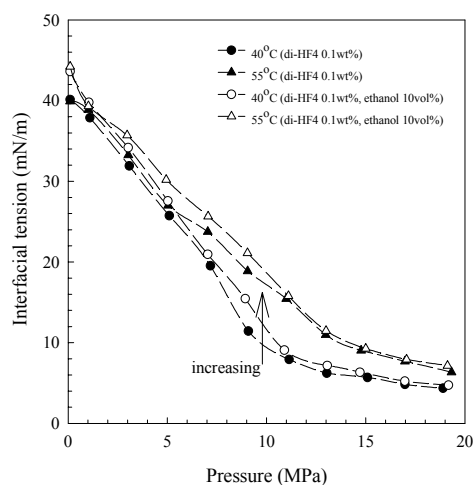


Figure 4. IFT of CO₂ + Nickel plating solution + di-HCF 4 + ethanol at 40°C, and 55°C

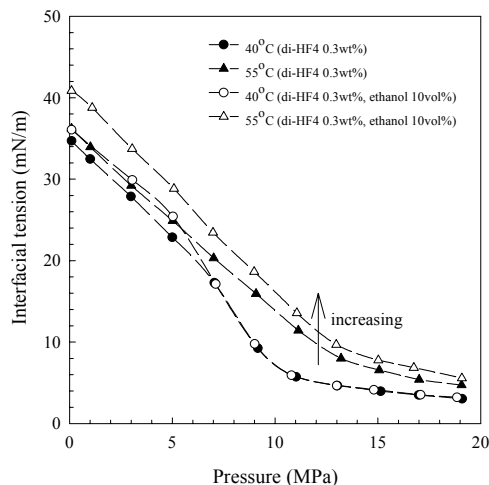


Figure 5. IFT of CO₂ + Nickel plating solution + di-HCF 4 + ethanol at 40°C, and 55°C.

Conclusion

We synthesized two nonionic H-F hybrid surfactants which have CO₂ philic tail and hydrophilic tail and measured the solubility of this surfactant in CO₂ and the IFT of CO₂/water and CO₂/nickel plating solution system. In IFT measurement, the effect of surfactant and ethanol was investigated. This research is will be up to the expectation of a help for understanding interface phenomena between CO₂ and polar chemicals such as water or nickel plating solution in supercritical CO₂.

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